BAKER TECHNOLOGY ASSOCIATES PROCESS SPREADSHEET

AUTOMATED COPPER / TIN / SOLDER PATTERN PLATING SYSTEM

Sta. No.	Process	Dwell Time (Min.)	Drip Time (Sec.)	Tank Size I.D. (Inches)				Approx. Gallons	D.T.O./Sump Data	Drain Data	Tanks	Tank Temp.	Coil Material		Exhaust Data	Process	Sta. No.
				D.O.T.	C.D.O.T.	Depth	Spacing				Mat'l/Insul.		Heat	Cool			
1	LOAD / UNLOAD			12	106	66	0.00	---		2"	Type 304 S.S./ Polypropylene					LOAD / UNLOAD	1
2	SPRAY RINSE			21	106	66	7.50	597		2"	Polypropylene					SPRAY RINSE	2
3	RACK STRIP			12	106	66	9.00	341		None	Type 316 S.S.	Ambient			Lateral Polypropylene	RACK STRIP	3
4	FLUOBORIC ACID DIP			12	106	66	19.00	341		2"	Polypropylene	Ambient				FLUOBORIC ACID DIP	4
5	SOLDER PLATE			28	106	66	9.00	797		2" Pump Suction	Polypropylene	75°F		Plastic		SOLDER PLATE	5
6	SPRAY RINSE			21	106	66	9.00	597		2"	Polypropylene					SPRAY RINSE	6
7-9	TIN PLATE	Up To 11		78	106	66	9.00	2,219		2" Pump Suction	Polypropylene	75°F		Plastic		TIN PLATE	7-9
10	SULFURIC ACID DIP			12	106	66	9.00	341		2"	Polypropylene	Ambient				SULFURIC ACID DIP	10
11-12	ACID CLEANER			23	106	66	18.00	654		2"	Polypropylene	130°F	Titanium		Lateral Polypropylene	ACID CLEANER	11-12
13	SPRAY RINSE			21	106	66	9.00	597		2"	Polypropylene					SPRAY RINSE	13
14	MICROETCH			15	106	66	9.00	427		2"	Polypropylene	115°F	Teflon		Lateral Polypropylene	MICROETCH	14
15	SPRAY RINSE			21	106	66	54.00	597		2"	Polypropylene					SPRAY RINSE	15
16	SULFURIC ACID DIP			12	106	66	9.00	341		2"	Polypropylene	Ambient				SULFURIC ACID DIP	16
17-19	ACID COPPER PLATE	82		78	106	66	9.00	2,219		4 Each 2"	Polypropylene	75°F		Titanium		ACID COPPER PLATE	17-19
20-22	ACID COPPER PLATE	82		78	106	66	9.00	2,219		4 Each 2"	Polypropylene	75°F		Titanium		ACID COPPER PLATE	20-22
23-25	ACID COPPER PLATE	82		78	106	66	9.00	2,219		4 Each 2"	Polypropylene	75°F		Titanium		ACID COPPER PLATE	23-25
26-28	ACID COPPER PLATE	82		78	106	66	9.00	2,219		4 Each 2"	Polypropylene	75°F		Titanium		ACID COPPER PLATE	26-28
29-31	ACID COPPER PLATE	82		78	106	66	9.00	2,219		4 Each 2"	Polypropylene	75°F		Titanium		ACID COPPER PLATE	29-31
32	ANODE SERVICE			18	106	66	7.50			2"	Type 304 S.S./ Polypropylene					ANODE SERVICE	32

Baker Technology Associates, Inc.
710 Wilshire Blvd. - Suite 610
Santa Monica, California 90401

Customer:		Date:	
Location:		Checked:	
Proposal No.:		Approved:	
System Title:	**AUTOMATED COPPER / TIN / SOLDER PATTERN PLATING SYSTEM**	Revision:	

BAKER TECHNOLOGY ASSOCIATES PROCESS SPREADSHEET

AUTOMATED COPPER / TIN / SOLDER PATTERN PLATING SYSTEM

Sta. No.	Process	Spargers			Controller Data				Rectifier Data	Filter Data Type/Rate	Remarks	Pumps		Mechanical Agitation				Process	Sta. No.
		Solution	Air	Eductors	Level	pH	Temp.	Cond.				Recirc.	Dosing	Bump	Vert.	Horiz.	Vibration		
1	LOAD / UNLOAD																	LOAD / UNLOAD	1
2	SPRAY RINSE										Alternating Pulse Sprays							SPRAY RINSE	2
3	RACK STRIP																	RACK STRIP	3
4	FLUOBORIC ACID DIP															Yes		FLUOBORIC ACID DIP	4
5	SOLDER PLATE	Yes					Yes									Yes		SOLDER PLATE	5
6	SPRAY RINSE										Alternating Pulse Sprays					Yes		SPRAY RINSE	6
7-9	TIN PLATE	Yes					Yes		4 Each 500A / 4V	Two (2) Turnovers Per Hour						Yes		TIN PLATE	7-9
10	SULFURIC ACID DIP															Yes		SULFURIC ACID DIP	10
11-12	ACID CLEANER				Yes		Yes									Yes		ACID CLEANER	11-12
13	SPRAY RINSE										Alternating Pulse Sprays					Yes		SPRAY RINSE	13
14	MICROETCH				Yes		Yes									Yes		MICROETCH	14
15	SPRAY RINSE										Alternating Pulse Sprays					Yes		SPRAY RINSE	15
16	SULFURIC ACID DIP															Yes		SULFURIC ACID DIP	16
17-19	ACID COPPER PLATE	Yes		Yes			Yes		6 Each 500A / 4V	Two (2) Turnovers Per Hour	One Eductor Pump Per Cell	3 Each				Yes		ACID COPPER PLATE	17-19
20-22	ACID COPPER PLATE	Yes		Yes			Yes		6 Each 500A / 4V	Two (2) Turnovers Per Hour	One Eductor Pump Per Cell	3 Each				Yes		ACID COPPER PLATE	20-22
23-25	ACID COPPER PLATE	Yes		Yes			Yes		6 Each 500A / 4V	Two (2) Turnovers Per Hour	One Eductor Pump Per Cell	3 Each				Yes		ACID COPPER PLATE	23-25
26-28	ACID COPPER PLATE	Yes		Yes			Yes		6 Each 500A / 4V	Two (2) Turnovers Per Hour	One Eductor Pump Per Cell	3 Each				Yes		ACID COPPER PLATE	26-28
29-31	ACID COPPER PLATE	Yes		Yes			Yes		2 Each 800A / 4V 4 Each 750A / 5V	Two (2) Turnovers Per Hour	One Eductor Pump Per Cell	3 Each				Yes		ACID COPPER PLATE	29-31
32	ANODE SERVICE																	ANODE SERVICE	32

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